

## N-Channel Power MOSFET

50V, 260mA, 2.5Ω

### FEATURES

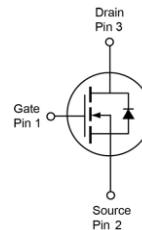
- Low  $R_{DS(ON)}$  to minimize conductive losses
- Logic level
- Low gate charge for fast power switching
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

### APPLICATIONS

- Low Side Load Switching
- Level Shift Circuits
- General Switch Circuits

### KEY PERFORMANCE PARAMETERS

PARAMETER	VALUE	UNIT
$V_{DS}$	50	V
$R_{DS(on)}$ (max)	$V_{GS} = 10V$	2.5
	$V_{GS} = 4.5V$	3
$Q_g$	1	nC


**SOT-23**


Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	50	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current (Note 1)	$I_D$	$T_A = 25^\circ\text{C}$	260
		$T_A = 125^\circ\text{C}$	117
Pulsed Drain Current	$I_{DM}$	1.04	A
Total Power Dissipation	$P_D$	$T_A = 25^\circ\text{C}$	357
		$T_A = 125^\circ\text{C}$	71
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	- 55 to +150	$^\circ\text{C}$

### THERMAL PERFORMANCE

PARAMETER	SYMBOL	MAXIMUM	UNIT
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	350	$^\circ\text{C/W}$

**Thermal Performance Note:**  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design. The  $R_{\theta JA}$  limit presented here is based on mounting on a 1 in<sup>2</sup> pad of 2 oz copper.

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	$BV_{DSS}$	50	--	--	V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	$V_{GS(TH)}$	0.8	1.1	1.6	V
Gate-Source Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	$I_{GSS}$	--	--	$\pm 100$	nA
Drain-Source Leakage Current	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}$	$I_{DSS}$	--	--	1	$\mu\text{A}$
	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}$ $T_J = 125^\circ\text{C}$		--	--	100	
Drain-Source On-State Resistance (Note 3)	$V_{GS} = 10\text{V}, I_D = 260\text{mA}$	$R_{DS(on)}$	--	1.1	2.5	$\Omega$
	$V_{GS} = 4.5\text{V}, I_D = 240\text{mA}$		--	1.2	3	
Forward Transconductance (Note 3)	$V_{DS} = 5\text{V}, I_D = 260\text{mA}$	$g_{fs}$	--	0.8	--	S
<b>Dynamic</b> (Note 3)						
Total Gate Charge	$V_{GS} = 10\text{V}, V_{DS} = 25\text{V},$ $I_D = 260\text{mA}$	$Q_g$	--	2	--	nC
Total Gate Charge	$V_{GS} = 4.5\text{V}, V_{DS} = 25\text{V},$ $I_D = 240\text{mA}$	$Q_g$	--	1	--	
Gate-Source Charge		$Q_{gs}$	--	0.3	--	
Gate-Drain Charge		$Q_{gd}$	--	0.3	--	
Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}$ $f = 1.0\text{MHz}$	$C_{iss}$	--	32	--	$\text{pF}$
Output Capacitance		$C_{oss}$	--	10	--	
Reverse Transfer Capacitance		$C_{rss}$	--	6	--	
<b>Switching</b> (Note 3)						
Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DS} = 25\text{V},$ $I_D = 260\text{mA}, R_G = 6\Omega$	$t_{d(on)}$	--	3	--	ns
Turn-On Rise Time		$t_r$	--	11	--	
Turn-Off Delay Time		$t_{d(off)}$	--	20	--	
Turn-Off Fall Time		$t_f$	--	48	--	
<b>Source-Drain Diode</b>						
Forward Voltage (Note 2)	$V_{GS} = 0\text{V}, I_S = 260\text{mA}$	$V_{SD}$	--	--	1.2	V
Reverse Recovery Time	$I_S = 260\text{mA},$ $di/dt = 100\text{A}/\mu\text{s}$	$t_{rr}$	--	13	--	ns
Reverse Recovery Charge		$Q_{rr}$	--	4	--	nC

**Notes:**

1. Silicon limited current only.
2. Pulse test: Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Switching time is essentially independent of operating temperature.

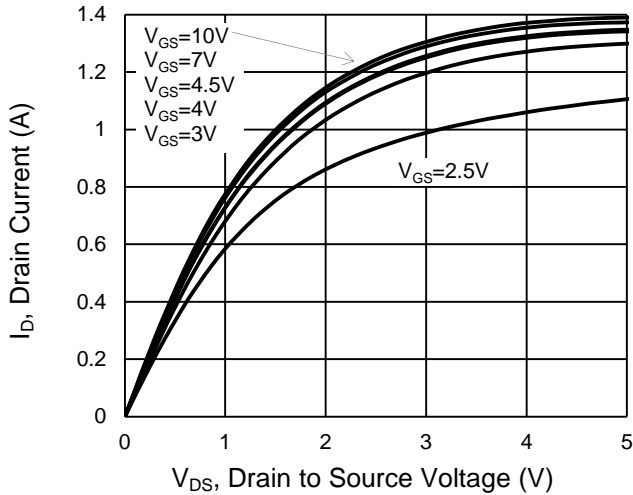
**ORDERING INFORMATION**

ORDERING CODE	PACKAGE	PACKING
BSS138 RFG	SOT-23	3,000pcs / 7" Reel

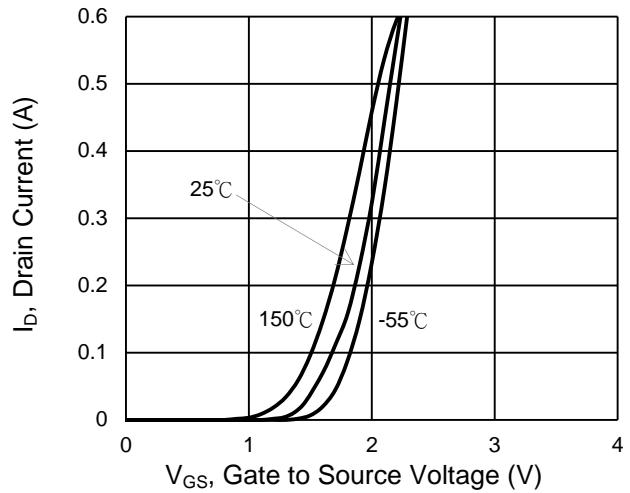
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

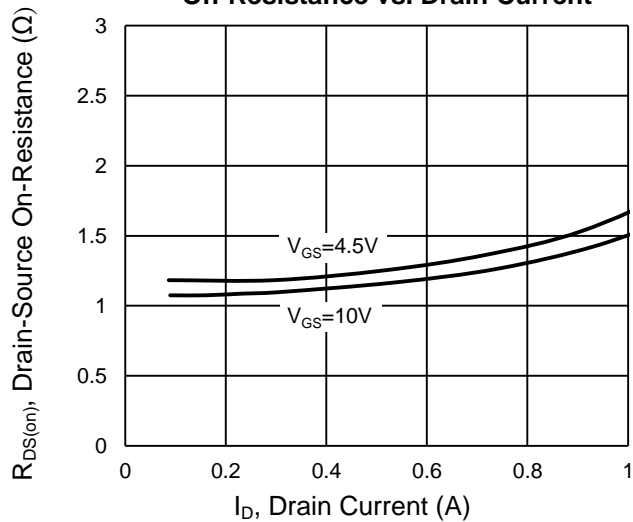
**Output Characteristics**



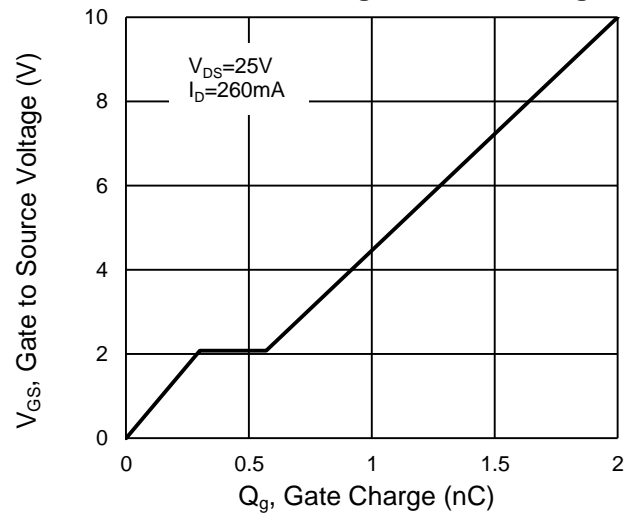
**Transfer Characteristics**



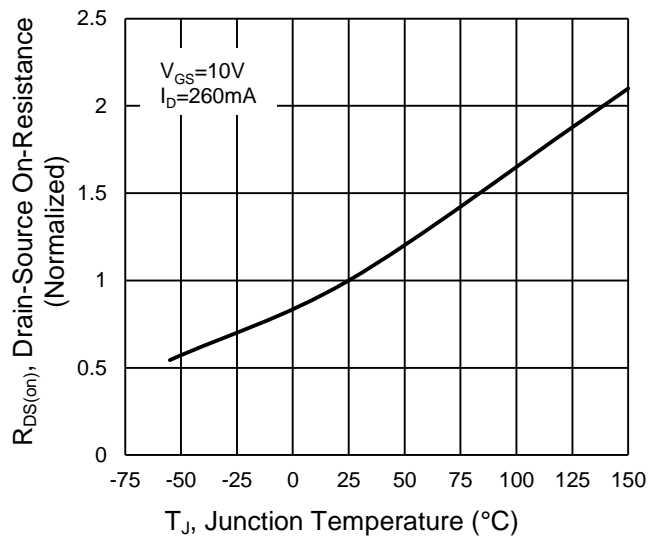
**On-Resistance vs. Drain Current**



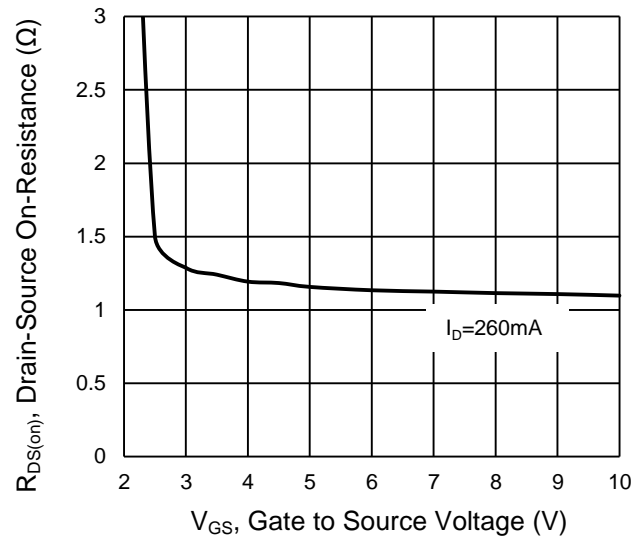
**Gate-Source Voltage vs. Gate Charge**



**On-Resistance vs. Junction Temperature**



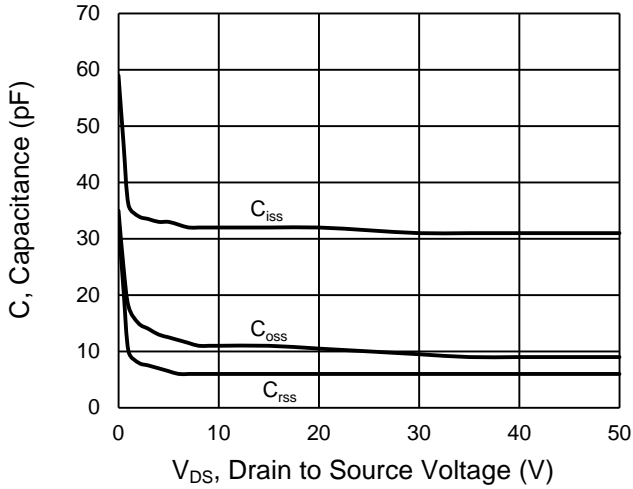
**On-Resistance vs. Gate-Source Voltage**



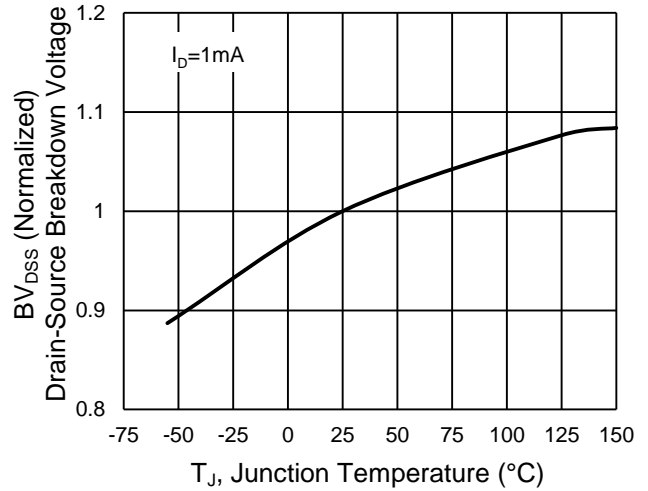
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

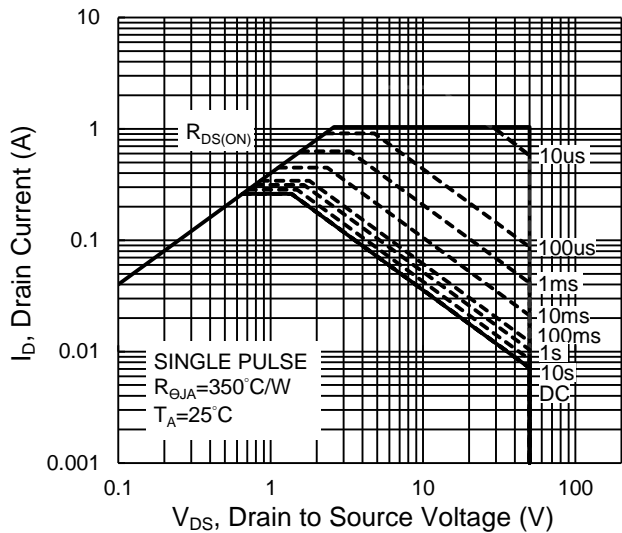
**Capacitance vs. Drain-Source Voltage**



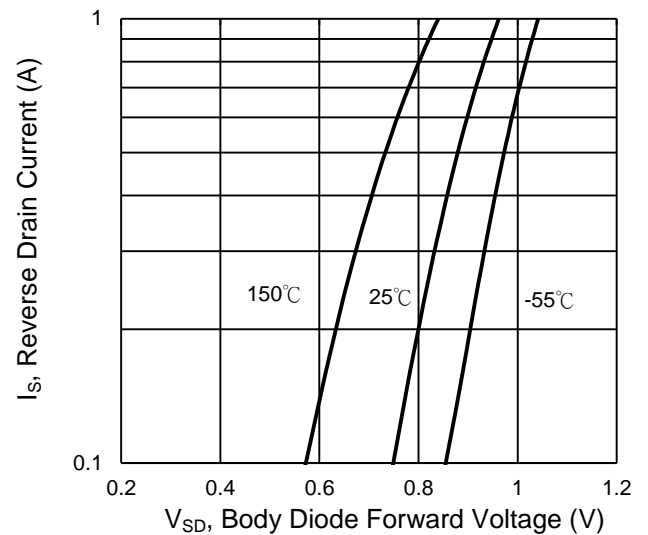
**$BV_{DSS}$  vs. Junction Temperature**



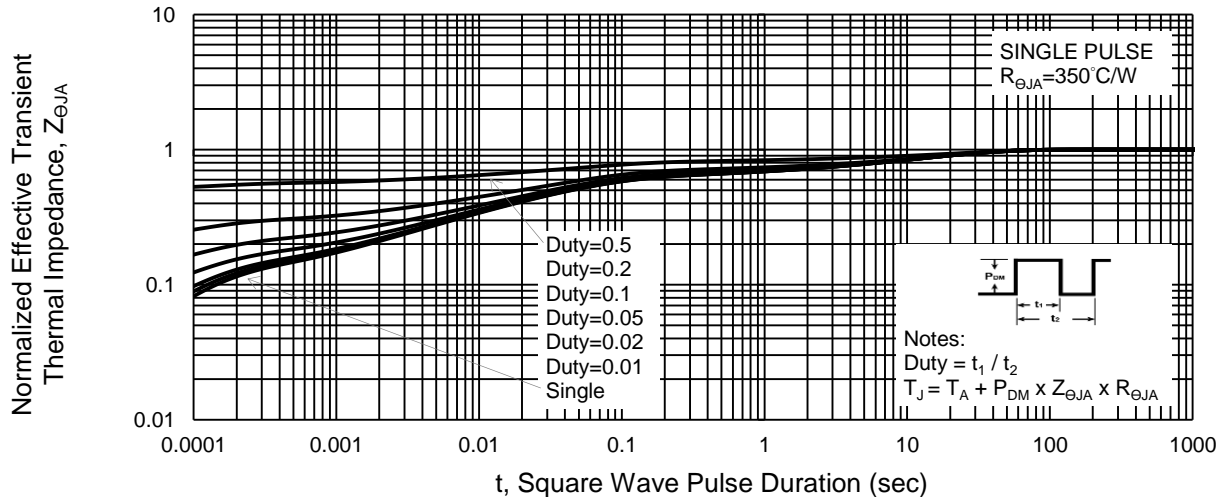
**Maximum Safe Operating Area, Junction-to-Ambient**



**Source-Drain Diode Forward Current vs. Voltage**

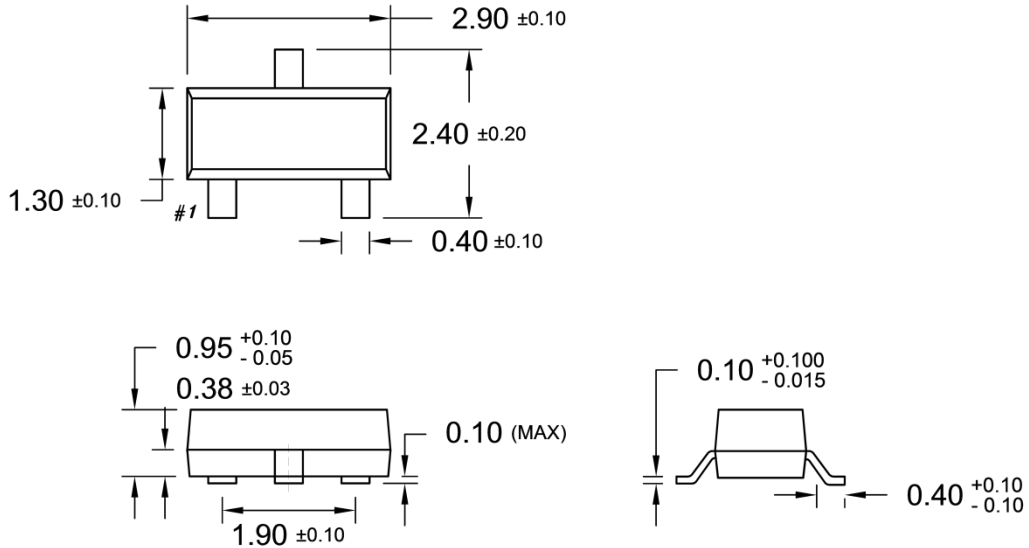


**Normalized Thermal Transient Impedance, Junction-to-Ambient**

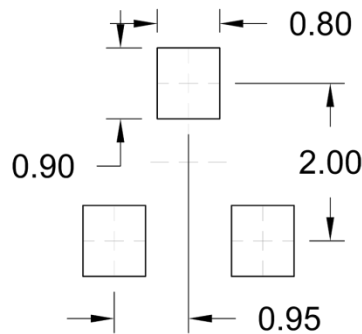


**PACKAGE OUTLINE DIMENSIONS** (Unit: Millimeters)

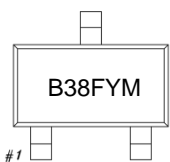
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**SUGGESTED PAD LAYOUT** (Unit: Millimeters)



**MARKING DIAGRAM**



- B38** = Device code
  - F** = Site Code
  - Y** = Year Code
  - M** = Month code
- |               |               |               |               |
|---------------|---------------|---------------|---------------|
| <b>O</b> =Jan | <b>P</b> =Feb | <b>Q</b> =Mar | <b>R</b> =Apr |
| <b>S</b> =May | <b>T</b> =Jun | <b>U</b> =Jul | <b>V</b> =Aug |
| <b>W</b> =Sep | <b>X</b> =Oct | <b>Y</b> =Nov | <b>Z</b> =Dec |

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